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Specifications

Connectors according to MIL C24308 - NFC 93425-HE5

	Materials and Platings
Shells	Steel with tin plating
Insulator	High temperature (peak at 260°C) glass-filled thermoplastic, UL 94V-0
Socket contact	Stamped and formed brass, selected gold in mating area; 2.54µm (100µ") min. tin on termination area, with entire contact under-plated 1.27µm (50µ") min. nickel
Rear insert	Brass, 3µm up to 5µm (118µ" up to 197µ") tinned over nickel 2µm up to 3 µm (78µ" to 118µ")
Boardlock	Tin plating 4μm up to 6μm (157μ" up to 236μ") over nickel 2μm up to 3μm (78μ" up to 118μ"), insertion force:
	Low Insertion Force = LIF (bronze)
	Zero Insertion Force = ZeFo (bronze)
Screwlock	Brass, $6\mu m$ up to $10\mu m$ (236μ " up to 394μ ") tinned over nickel $2\mu m$ up to $3\mu m$ (78μ " up to 118μ ")
Grounding	Grounding strap: brass, 4µm up to 6µm tin plating over nickel 2µm up to 3µm (78µ" up to 118µ")

	Electrical Data
Current rating	3A
Voltage rating	300V AC/rms 50Hz
Withstanding voltage	1000V AC/rms 50Hz for one minute
Insulation resistance	5000ΜΩ
Contact resistance	10mΩ max

	Climatic Data
Operating temperature	85°C, peak at 105°C
Damp heat	56 days (40°C - 95% HR)

Mechanical Data

Single contact insertion force Single contact withdrawal force

1.2N < F < 2.5N 0.4N min

LIF boardlock Coplanarity of contacts 8N max per connector 0.2mm (.008") max

Mating and unmating force

Unit: N

No. of Cts	Mate (max)	Unmate (min)	
9 (size E)	30	3.5	
15 (size A)	50	4.5	
25 (size B)	83	8.0	

Amphenol SMT D-Sub is offered in right angle, receptacle with brackets, as an industry standard for I / O connections.

Boardlock features:

-LIF (Low Insertion Force) boardlock especially designed to be fully compatible with pick and place machine.

-ZeFo (Zero Force Insertion) boardlock has been designed so that once placed and expanded, secures a safe locking.

Designed for Pick and Place SMT process

Industrial

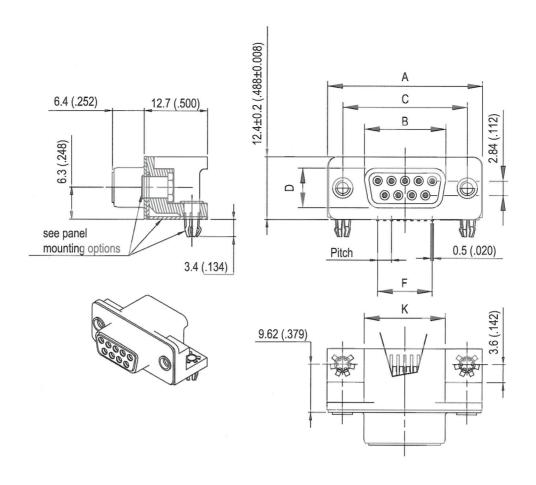
Telecom

· Any industry standard I/O connections

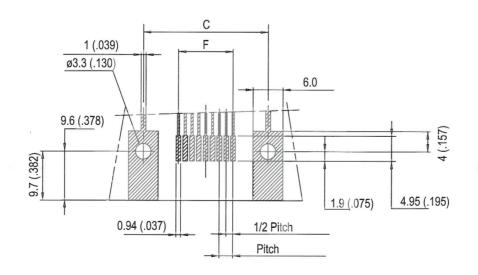




Shell Size Dimensions



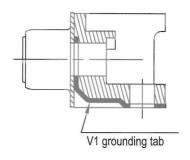
PCB LAYOUT

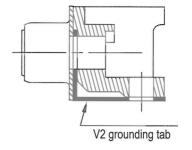


SHELL	mm (inch)						
SIZE	Α	В	С	D	PITCH	F	K
	+0.05 (.002) -0.1 (.004)	0 -0.2 (.008)	±0.1 (.004)	0 -0.25 (.01)			
E	31.15 (1.226)		25 (.984)	8.03 (.316)	2.74 (.1078)	10.97 (.432)	16.3 (.642)
A	39.4 (1.551)	24.8 (.976)	33.3 (1.311)	8.03 (.316)	2.74 (.1078)	19.2 (.756)	24.6 (.968)
В	53.3 (2.098)	38.5 (1.515)	47 (1.850)	8.03 (.316)	2.76 (.1086)	33.12 (1.304)	38.3 (1.508)

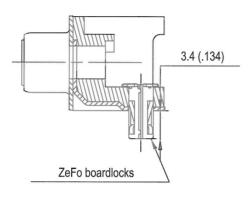
Panel mounting option

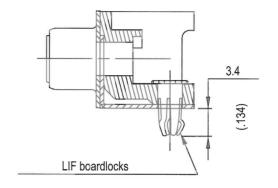
GROUNDING TABS:

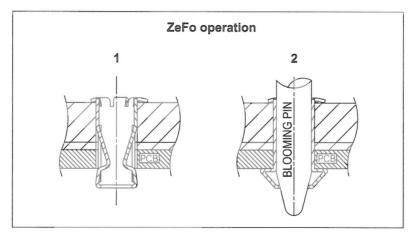




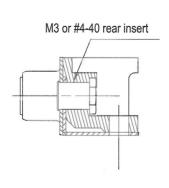
BOARDLOCKS:

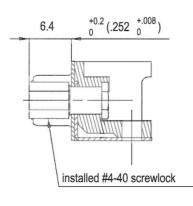


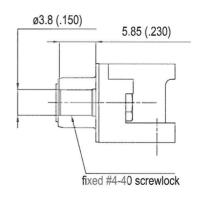




FLANGES ACCESSORIES:







Theaded Rear

Installed Front Female Fixed Front Female

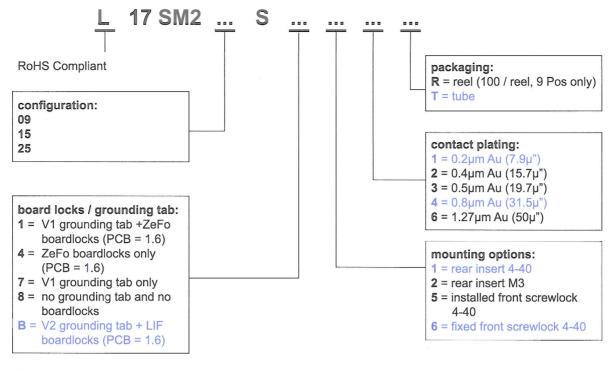
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Ampheno

How to order



: Standard options

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For special request, please consult factory

Memo		

Do not hesitate to contact us for further information

Amphenol

Amphenol IT & Communication Products

Block A3/A4, The 4th Industrial District of Industrial Headquarters, Dong Keng Road Gong Ming Town, Shen Zhen China Fax:+86(0)755 2754 9955

Technical Support
Tel:+86(0)755 2717 7945
Info-dsub@amphenol.com.cn
http://www.dsubconnector.com